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PATENT



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Case	Docket No	SS-714-01
Data	June 19	2000

COMMISSIONER OF PATENTS AND TRADEMARKS Washington, D.C. 20231

Sir:

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Transmitted herewith for filing is the patent application of:

Inventor:

VLADIMIR VAGANOV

For:

METHOD FOR FABRICATING MICROSTRUCTURES WITH DEEP ANISOTROPIC

ETCHING OF THICK SILICON WAFERS

Enclosed are

	CTOS	ed are:		
D	24	Pages of specification	1 Pages of abstract18 Pages of cla	ims
W _	_16	Sheets of drawing	X_formalinformal	
	X	An assignment of the inve	ention toEcotech International, submitted with	<u>. </u>
#}		separate transmitta	1	
		A certified copy applicati	on(s)	
j	 .		from which priority is claimed.	

		CLAIMS AS FILED		
	NUMBER FILED	NUMBER EXTRA	RATE	BASIC FEE \$690.00
TOTAL CLAIMS	115 - 20 =	95	x \$ 18.00	\$1,710.00
INDEPENDENT CLAIMS	3 - 3 =	0	x \$ 78.00	0
Multiple Depen	dent Claims, if	any 0	x \$260.00	0

Filing Fee \$ $\frac{2,400.00}{}$

 \overline{X} A verified statement that this is a filing by a small entity is attached. The fee due is fifty percentum of the above.

Filing Fee \$ 1,200.00

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additional fees as	set forth in 37 (authorized to charge C.F.R. 1.16 and 1.17 <u>310</u> . A duplicate of	wnich may be requ	ired or credit
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THOMAS E. SCHATZEL Reg. No. 22,611

Date: 06-19-00

Attorney for Applicant

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